Product Change Notification

Change Notification #:	**116522 - 03**
Change Title:	**Select Intel® Data Center Blocks for Cloud, ZSB2224BPHY1, ZSB2224BPAF1 & ZSB2224BPAF2, PCN 116522-03, Product Design, Order Code, Replacing select SSD components marked for End of Life Reason for Revision: Changed number of cache devices in ZSB2224BPAF2**
Date of Publication:	**October 24, 2018**

Key Characteristics of the Change:

Product Design, Order Code

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	October 31, 2018

Description of Change to the Customer:

Reason for Revision: Changed number of cache devices in ZSB2224BPAF2

Intel Corporation is implementing changes on the Intel® Data Center Blocks for Cloud ZSB2224BPHY1, ZSB2224BPAF1 and ZSB2224BPAF2.

1. The specific Intel SSDs are currently on an End of Life plan will be replaced with new models of equivalent capacity as follows:

    - Intel® SSD DC S4500 will be replaced with Intel® SSD D3 S4510
    - Intel® SSD DC S4600 will be replaced with Intel® SSD D3 S4610
    - Intel® SSD DC P4600 will be replaced with Intel® SSD DC P4610

2. In addition, the Intel® SSD DC P3100 (256GB, M.2, 80mm) will be replaced with the Intel® SSD DC P4101 (512GB, M.2, 80mm)

3. Changed number of Intel® SSD P4800 (375GB, 2.5" SFF U.2) cache devices from two devices per compute node to one device per compute node in ZSB2224BPAF2 model.

Customer Impact of Change and Recommended Action:

Intel does not expect any impact to customers from these changes, but encourages customers to understand the changes and determine the impact on their applications.

The date of "Customer Must be Ready to Receive Post-Conversion Material" is the projected date that customers must be prepared to start receiving the Post-Converted Material. After this date, the Pre-Conversion SKUs will be discontinued and no longer guaranteed. They may be available only on a first come first serve basis, while supply lasts.

Please contact your local Intel Field Sales Rep if you have any further questions about these changes.

Products Affected / Intel Ordering Codes:

Product Code	Pre Change MM#	Post Change MM#
ZSB2224BPAF2	984304	999A7D
ZSB2224BPAF1	984305	999A7F
ZSB2224BPHY1	984306	999A7G

PCN Revision History:

Date of Revision:	Revision Number:	Reason:
October 1, 2018	00	Originally Published PCN
October 11, 2018	01	Added SSD P3100 to the list of devices to be replaced
October 17, 2018	02	Increased capacity of the SSD P4101 replacing the SSD P3100
October 24, 2018	03	Changed number of cache devices in ZSB2224BPAF2

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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